ON Semiconductor

FINAL PRODUCT/PROCESS CHANGE NOTIFICATION #16667

Generic Copy

Issue Date: 24-Jun-2011

TITLE: Wire Size Change in SC88 Package on Gate Pad for MOSFET Products

PROPOSED FIRST SHIP DATE: 01-Oct-2011

AFFECTED CHANGE CATEGORY(S): ON Semiconductor SC88 Assembly – Wire Bond

FOR ANY QUESTIONS CONCERNING THIS NOTIFICATION:
Contact your local ON Semiconductor Sales Office or Jason Jeong <Jason.Jeong@onsemi.com>

SAMPLES: Contact your local ON Semiconductor Sales Office or Jason Jeong <Jason.Jeong@onsemi.com>

ADDITIONAL RELIABILITY DATA: Available
Contact your local ON Semiconductor Sales Office or Donna Scheuch <d.scheuch@onsemi.com>

NOTIFICATION TYPE:

Final Product/Process Change Notification (FPCN)

Final change notification sent to customers. FPCNs are issued at least 90 days prior to implementation of the change.

ON Semiconductor will consider this change approved unless specific conditions of acceptance are provided in writing within 30 days of receipt of this notice. To do so, contact <quality@onsemi.com>.

DESCRIPTION AND PURPOSE:

ON Semiconductor is notifying customers of its use of 0.8mil wire in place of 2mil wire on gate pad for their SC88 Packaged Products assembled with MOSFET Die. This change is being done to optimize the gate wire of the package to align to device requirements.

Reliability Qualification and full electrical characterization over temperature has been performed.

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RELIABILITY DATA SUMMARY:

Reliability Test Results:

Device Name: NTJS3157NT1G

Test: High Temperature Gate Bias (HTGB)
Conditions: Ta = 150°C, Vgs = 100% Max Rated Vgs, Duration : 1008-Hrs, 3-Lots
Results: 0/252

Test: Temperature Cycling (TC-PC)
Conditions: Ta = -65°C/150°C, Air-to-Air, Dwell ≥ 10-min, 1000-cycles, 3-Lot
Results: 0/252

Test: Intermittent Operating Life (IOL-PC)
Conditions: Ta = 25°C, Delta Tj = 100°C, 2-min on/off, 15K- cycle, 3-Lot
Results: 0/252

ELECTRICAL CHARACTERISTIC SUMMARY:

There is no change in electrical parametric performance. Characterization data is available upon request.

CHANGED PART IDENTIFICATION:

There will be no physical change with products assembled with 0.8mil wire in place of 2mil wire. Products (listed on this FPCN) assembled with 0.8mil wire from the ON Semiconductor facility in Leshan, China will have a Finish Good Date Code representing Work Week 40, 2011 or newer.

List of affected General Parts:

NTJS3151PT1G
NTJS3151PT2G
NTJS3157NT1
NTJS3157NT1G
NTJS3157NT2G
NTJS4151PT1G
NTJS4160NT1G